

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a semiconductor chip having a semiconductor element or an integrated circuit formed in the semiconductor chip, a low
5 dielectric constant insulating film formed on a surface of the semiconductor chip, and a plurality of bump electrodes being provided on the surface of the semiconductor chip, a wiring board having a plurality of connecting electrodes being electrically connected
10 to the bump electrodes, and a resin molding filled in a space between the semiconductor chip and the wiring board, the electrically connected bump electrodes and the connecting electrodes being arranged in the space, wherein the resin molding is formed of a resin having
15 a flux function and changed from liquid to solid when the bump electrodes are in a molten state.